

BONDTM COMPACT

Urethane Wood Flooring Adhesive | Contains 600 milliliters, 0.6 litres

PRODUCT DESCRIPTION: Bond™ Compact is a urethane based, highstrength adhesive for professional wood flooring installation. It does not contain isocyanates, any solvents or other hazardous materials. It is therefore ozone and environmentally safe.

Bond™ Compact spreads easily with a specially designed gun and has a non-slump formula to allow the ridges to bridge gaps between wood flooring and sub floor. Beads are spread approx. 3 inch apart on the sub floor. Vary height of beads to eliminate hollow spots especially when installing long planks. Since there is no water or solvent present it will not cause dimensional changes to wood flooring. Bond™ Compact was designed for an easier installation of long planks on uneven or unstable sub floors instead of nail-down installation and allows for the natural movement of the floor. It can also be used to glue wood molding. The adhesive spreads easily and has a non-slump formula that will help insure contact and adhesive transfer. It allows fast installation even with complicated patterns due to its strong green grab. There is no flash time required, so installation can commence immediately. Rolling is neither required nor recommended. It offers superior flexibility and is designed to keep the flooring in place, yet allow for normal movement during seasonal changes to the flooring.

PRE-INSTALLATION CHECKLIST: A successful installation requires proper preparation of the sub floor. Read and understand all applicable guidelines and technical data sheets before installation. Follow industry standards and flooring manufacturer's recommendations for sub floor moisture content, design, layout and application of flooring materials. All slab constructions must meet the specific requirements of the floor covering to be installed.

SUB FLOOR EXAMINATION: Prior to installation, the sub floor must be checked according to NWFA installation guidelines. It must be solid and sound, flat, permanently dry, clean, free of chaps, indentations and anti-adherents, as well as resistant to pressure and tension. Moisture content of all floors must be measured before installation. Moisture content in concrete sub floors must be below 3#/24h/1,000 sq. ft. using the Calcium Chloride Test or below 75% RH using an in-situ probe. All wood floors should have 6-9% moisture content at installation. There should be no more than a 4-5% variance in moisture content between the wood flooring and any wood sub floor. See NWFA guidelines and the wood flooring manufacturer's recommendations for details.

SUB FLOOR PREPARATION: Depending on type and condition of sub floor, a mechanical treatment (e.g. mechanical brushing, grinding or sanding) may be required. Intensity of such work must be determined at the site by the installer. Dust, paint, residual adhesives or other surface contaminants must be removed by suitable means. Cleaning the surface with an industrial vacuum cleaner is recommended. Cracks and gaps must be filled with concrete crack filler unless they are expansion joints. Level when necessary to 3/16 inches within 10 feet. Heated sub floors must be primed.

INSTALLATION PROCEDURE: Spread the Adhesive using the sausage gun. Apply beads approx. ½" thick and 3" apart. Lay the flooring into the adhesive, position correctly and press down firmly. There is no flash time, so installation should begin immediately. Lay the flooring into the adhesive, correctly position it and press down firmly. Rolling is neither required nor recommended. Be sure to check the boards at regular intervals to make certain good adhesive transfer from sub floor to flooring is achieved. Bowed boards or boards over low spots should be weighted down until the adhesive cures.

LIMITATIONS: When using other than Divine Flooring products in conjunction with Divine Flooring primers, sealers, leveling compounds, or adhesives, Divine Flooring denies any and all responsibility for any ensuing problems and/or damages without prior written authorization from Divine Flooring. Do not install solid wood below grade. Do not use on concrete with curing agents or sealers except approved Divine Flooring Sealers. Do not use on damp sub floors. Do not

install wood flooring with a moisture reading above 9%. Do not use adhesive as a leveling material.

In case of accident, injury, spill or exposure, see MSDS sheet for information. Consult technical data sheet at divinefloor.com for updated information. The foregoing representations are based on the results of our most current product and material testing within a controlled environment and are of a non-obligatory advisory nature only. As such, they do not constitute an express or implied warranty of any kind including the Warranty of Merchantability and/or Fitness for a Particular Purpose. Because we have no control over the actual quality of workmanship, materials used and worksite conditions, Divine Flooring will in no event be liable for any incidental and/or consequential damages. herefore, we strongly recommend that prior on-site testing be conducted to refer to and study the suitability of the product for the intended purpose. With the release of this technical information sheet all its prior versions become invalid.

For warranty and warranty disclaimer information and MSDS data sheets please visit divinefloor.com.

GENERAL FEATURES: moisture cured urethane, LEED qualified, contains no isocyanates, contains no water, high shear strength, contains no chlorinated solvents, contains no solvents, contains no VOC, certified "green", certified "very low emission", nonflammable, high solids content, ozone friendly, freeze/thaw stable

INSTALLATION FEATURES: grabs quicker, less slippage, wet lay - no flash time required, superior green grab, non-slump formula, bridges normal sub floor variations, eliminates hollow spots, very low odor, cleans with acetone, excellent spread rate, higher temp & RH will shorten drying time, no risk of sensitization

LONG TERM FEATURES: resistant against aging, remains elastic, suitable for radiant heat systems, allows normal dimensional changes in wood flooring, adhesive is waterproof when cured, eliminates hollow spots, no health hazards

APPROVED FLOORING: Planks, up to 7" wide

APPROVED SUB FLOORS: Concrete slabs, OSB (underlayment grade), plywood (underlayment grade), vinyl (well bonded, grinded, tested negative for asbestos), ceramic tiles, stone, terrazzo, cured leveling compounds, radiant heated sub floors

For approved primers, sealers and levelling compounds, please contact a Divine Flooring Sales Representative or a Divine Flooring Authorized Dealer.

APPROVED TROWELS AND SPREAD RATE: Ridges 1/4" x 1/4": up to 100 LF/unit

CURE TIME UNTIL NORMAL TRAFFIC: Approx. 48 hours

 $\textbf{CLEAN-UP:} \ \ \textbf{Use acetone while wet, use plastic scraper and terry cloth when dry}$

TEMPERATURE RANGE DURING INSTALLATION: 50°-90°F
RELATIVE HUMIDITY RANGE DURING INSTALLATION: 30% - 80%
PACKAGING SIZE: 20.3 fl. oz. aluminum sausage pack, 20 count case

WEIGHT [LBS./GAL.]: 10.6

COLOR: Cream STORAGE: Dry

SHELF LIFE: 12 Months in original, unopened container

OpenTime	30% R/H	50% R/H	80% R/H
50°F/10°C	40 mins.	35 mins.	30 mins.
70°F/21°C	35 mins.	30 mins.	25 mins.
90°F/32°C	30 mins.	25 mins.	20 mins.



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